



Product Change Notification

Change Notification #: 118487-00
Change Title: Select Intel® SSD D7-P5500 Series, and Intel® SSD D7-P5600 Series for Cisco*
PCN 118487-00, Product Material, Add alternate DRAM to ADP BOM
Date of Publication: September 17, 2021

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	December 17, 2021
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Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

1. Current DRAM IPN# J87850-001 EOL-ing (Nanya) and changing to new IPN# J87850-002 (Nanya), affect ADP ME SFF 3.2T, ADP SE SFF 3.8T, ADP AICx8 6.4T.
2. Current DRAM IPN# K47704-001 EOL-ing (Samsung) and changing to new IPN# K92222-002 (Hynix), affected ADP ME 6.4T and ADP SE 7.6T

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

*Other names and brands may be claimed as the property of others.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	TA	SA	PBA
Intel® SSD D7-P5500 Series (7.68TB, 2.5in PCIe 4.0 x4, 3D3, TLC) Cisco Single Pack	SSDPF2KX076T9K1	99A0HJ	K90148-100	K90171-100	K83463-103
Intel® SSD D7-P5600 Series (6.4TB, 2.5in PCIe 4.0 x4, 3D3, TLC) Cisco Single Pack	SSDPF2KE064T9K1	99A0HL	K90151-100	K90176-100	K83463-103
Intel® SSD D7-P5500 Series (3.84TB, 2.5in PCIe 4.0 x4, 3D3, TLC) Cisco Single Pack	SSDPF2KX038T9K1	99A0HR	K90147-100	K90170-100	K83461-103
Intel® SSD D7-P5600 Series (3.2TB, 2.5in PCIe 4.0 x4, 3D3, TLC) Cisco Single Pack	SSDPF2KE032T9K1	99A0HV	K90150-100	K90175-100	K83461-103

PCN Revision History:

Date of Revision:

September 17, 2021

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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